











TPD2E1B06

SLVSC77D -AUGUST 2013-REVISED APRIL 2016

TPD2E1B06 Dual-Channel High-Speed ESD Protection Device

Features

- Provides System Level ESD Protection for Low Voltage IO Interface
- IEC 61000-4-2 Level 4 ESD Rating
- Low IO Capacitance: 0.85 pF (Typical)
- DC Breakdown Voltage: 7 V (Minimum)
- Ultra-Low Leakage Current: 10 nA (Maximum)
- Low ESD Clamping Voltage
- Temperature Range: -40°C to 125°C
- Small Easy-to-Route DRL package

Applications

- **Gaming Machines**
- eBooks
- Portable Media Players
- **Digital Cameras**

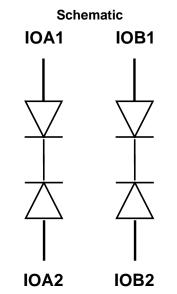
3 Description

The TPD2E1B06 device is a dual-channel, ultra-low capacitance ESD protection device. It offers ±10-KV IEC contact ESD protection. Its 1-pF line capacitance makes it suitable for a wide range of applications. Typical application interfaces are USB 2.0, LVDS, and I2C. The TPD2E1B06 device has two common layout methods, and both are highlighted in *Layout*.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)		
TPD2E1B06	SOT (6)	1.60 mm × 1.20 mm		

(1) For all available packages, see the orderable addendum at the end of the data sheet.



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1	Features 1	7.3 Feature Description	7
2	Applications 1	7.4 Device Functional Modes	7
3	Description 1	8 Application and Implementation	8
4	Revision History2	8.1 Application Information	8
5	Pin Configuration and Functions	8.2 Typical Application	8
6	Specifications3	9 Power Supply Recommendations	10
•	6.1 Absolute Maximum Ratings	10 Layout	10
	6.2 ESD Ratings	10.1 Layout Guidelines	. 10
	6.3 Recommended Operating Conditions 4	10.2 Layout Examples	. 10
	6.4 Thermal Information	11 Device and Documentation Support	11
	6.5 Electrical Characteristics	11.1 Community Resources	. 11
	6.6 Typical Characteristics	11.2 Trademarks	. 11
7	Detailed Description 7	11.3 Electrostatic Discharge Caution	. 11
-	7.1 Overview 7	11.4 Glossary	. 11
	7.2 Functional Block Diagram	12 Mechanical, Packaging, and Orderable Information	11

4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision C (September 2013) to Revision D

Page

Changes from Revision B (September 2013) to Revision C

Page

Changes from Revision A (August 2013) to Revision B

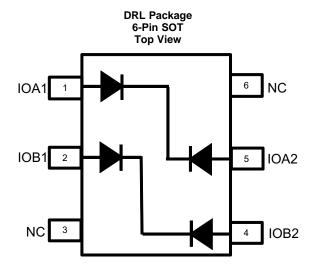
Changes from Original (July 2013) to Revision A

Page

Page



5 Pin Configuration and Functions



Pin Functions

PIN		TYPE	DESCRIPTION	USACE			
NAME	NO.	ITPE	DESCRIPTION	USAGE			
IOA1	1	I/O					
IOA2	5	I/O	FCD must set and share and	See Application Information.			
IOB1	2	I/O	ESD protected channel				
IOB2	4	I/O					
NC	3, 6	NC	No connect	Can be left floating, grounded, or connected to VCC			

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
	Operating temperature	-40	125	°C
I _{PP}	Peak pulse current (tp = $8/20 \mu s$) ⁽²⁾		2.5	Α
P _{PP}	Peak pulse power (tp = $8/20 \mu s$) ⁽²⁾		35	W
T _{stg}	Storage temperature	-65	155	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD) Electrostatic discharge	Electrostatio discharge	IEC 61000-4-2 contact discharge ⁽¹⁾	±10000	\/
	IEC 61000-4-2 air-gap discharge ⁽¹⁾	±15000	V	

(1) Using Routing Option 1 or 2 as shown in Figure 13 or Figure 14.

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⁽²⁾ Using Routing Option 1 or 2 as shown in Figure 13 or Figure 14.



6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{IO}	Pin IOA1 to IOA2; Pin IOB1 to IOB2	-5.5	5.5	V
T _A	Operating free-air temperature	-40	125	°C

6.4 Thermal Information

over operating free-air temperature range (unless otherwise noted)

		TPD2E1B06	
	THERMAL METRIC ⁽¹⁾	DRL (SOT)	UNIT
		6 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	349.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	120.5	°C/W
$R\theta_{\theta JB}$	Junction-to-board thermal resistance	171.4	°C/W
ΨЈТ	Junction-to-top characterization parameter	10.8	°C/W
ΨЈВ	Junction-to-board characterization parameter	169.4	°C/W

⁽¹⁾ For more information about traditional and new thermal metrics, the Semiconductor and IC Package Thermal Metrics application report,

6.5 Electrical Characteristics

over operating free-air temperature range. (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{RWM}	Reverse standoff voltage				5.5	V
	Clamp voltage with ESD	I _{PP} = 1 A, TLP, I/O to GND ⁽¹⁾⁽²⁾		11		
V_{CLAMP}	strike	$I_{PP} = 5 \text{ A}$, TLP, I/O to $GND^{(1)(2)}$	15		V	
1.7	Clamp voltage with ESD	$I_{PP} = 1 \text{ A, TLP, GND to I/O}$		11		
V_{CLAMP}	strike	$I_{PP} = 5 \text{ A}$, TLP, GND to I/O $^{(1)(2)}$	15			V
R _{DYN}	Dynamic resistance			0.9		Ω
C _{L1}	Pin 2 and 5 capacitance	Pin 1 and 4 = GND, f = 1 MHz, $V_{BIAS} = 2.5 V^{(2)(3)}$		0.85		рF
C _{L2}	Pin 1 and 4 capacitance	Pin 2 and 5 = GND, f = 1 MHz, $V_{BIAS} = 2.5 V^{(2)(4)}$		1.05		pF
V_{BR}	Break-down voltage	I _{IO} = 1 mA	7		9.5	V
I _{LEAK}	Leakage current	V _{BIAS} = +2.5 V		1	10	nA

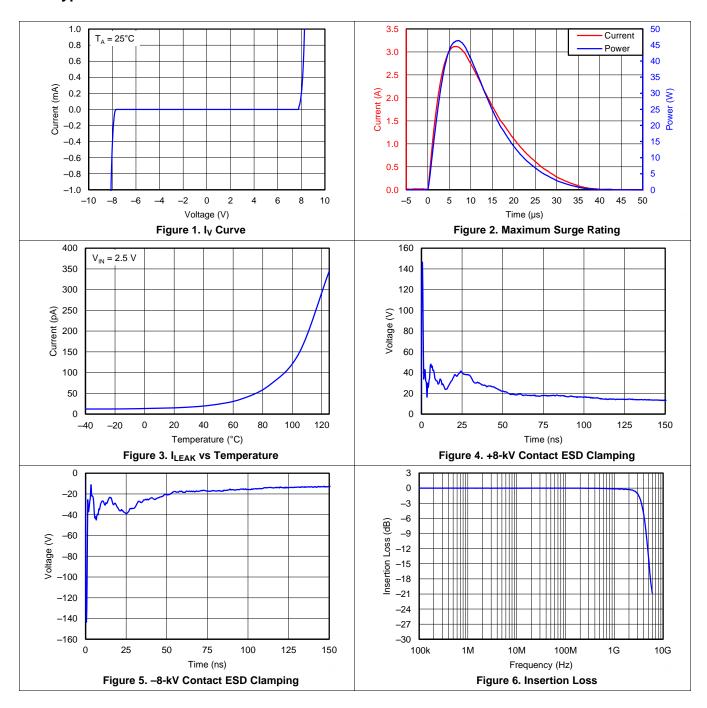
Transmission line pulse with rise time 10 ns and pulse width 100 ns.

 $T_A = 25^{\circ}C$

Using Routing Option 1, Figure 13.
Using Routing Option 2, Figure 14.

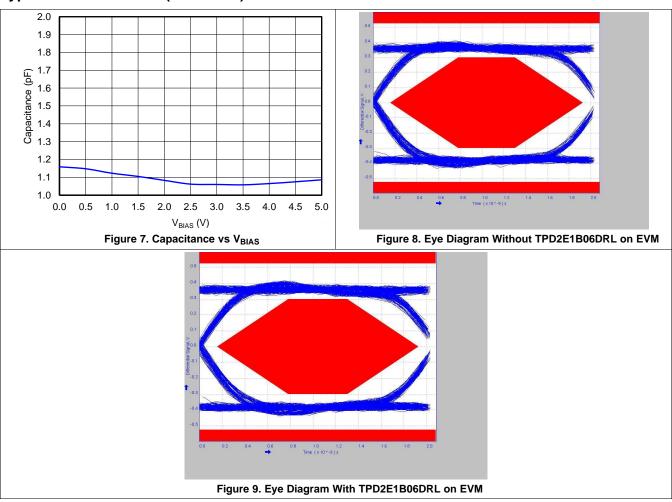


6.6 Typical Characteristics





Typical Characteristics (continued)



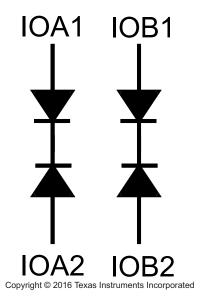


7 Detailed Description

7.1 Overview

The TPD2E1B06 is a bidirectional, low-capacitance, two-channel ESD clamping device. It has more than IEC 61000-4-2 Level 4 ESD Rating. The low IO capacitance makes the device a good fit for a wide range of data speeds. Common applications include USB 2.0, LVDS, and I2C.

7.2 Functional Block Diagram



7.3 Feature Description

The TPD2E1B06 device provides robust system level IEC protection. This device protects circuit from ESD strikes up to ± 10 -kV contact and ± 15 -kV air-gap specified in the IEC 61000-4-2 level 4. It also handles up to 2.5-A surge current (IEC61000-4-5 8/20 μ s). The I/O capacitance of 0.85 pF supports high data rates. The device has a small dynamic resistance of 0.9 Ω , making clamping voltage low when the device is actively protecting other circuits. With low capacitance and dynamic resistance, the TPD2E1B06 is a good fit for interfaces like USB 2.0, LVDS, and I2C. The breakdown is bidirectional so that this protection device is especially good for bidirectional signals like audio lines. Low leakage allows the diode to conserve power when working below the V_{RWM}. The temperature range of -40°C to 125°C makes this ESD device work at extensive temperatures in most environments.

7.4 Device Functional Modes

The TPD2E1B06 is a passive clamp that has low leakage during normal operation when the voltage across each channel is below V_{RWM} and activates when the it goes above V_{BR} . During IEC ESD events, transient voltages will be clamped. When the voltages on the protected lines fall below the trigger voltage, the device reverts back to the low-leakage passive state.



Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

When a system contains a human interface connector, the system becomes vulnerable to large system-level ESD strikes that standard ICs cannot survive. TVS ESD protection diodes are typically used to suppress ESD at these connectors. There are 2 channels of back-to-back diodes in TPD2E1B06. The device is typically used to provide a path to ground for dissipating ESD events between a human interface connector and a system. As the current from ESD passes through the device, only a small voltage drop is present across the diode structure. This is the voltage presented to the protected IC. The low R_{DYN} of the triggered TVS holds this voltage, V_{CLAMP}, to a tolerable level to the protected IC.

8.2 Typical Application

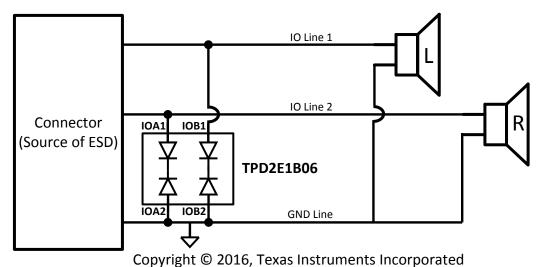


Figure 10. Typical Application Schematic

8.2.1 Design Requirements

In this design example, a TPD2E1B06 is used to protect audio channels. Table 1 lists the system parameters.

Table 1. Design Parameters

DESIGN PARAMETER	VALUE
Audio Amplifier Class	AB
Audio signal voltage range	−3 V to 3 V
Audio frequency content	20 Hz to 20 kHz
Required IEC 61000-4-2 ESD Protection	±8-kV Contact/ ±15-kV Air-Gap

8.2.2 Detailed Design Procedure

For some parameters, the designer must ensure the following before designing:

- Voltage range on the protected line must not exceed the reverse standoff voltage of the TVS diode(s) (V_{RWM})
- Operating frequency is supported by the I/O capacitance C_{IO} of the TVS diode



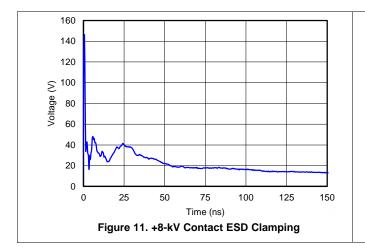
IEC 61000-4-2 protection requirement is covered by the IEC performance of the TVS diode

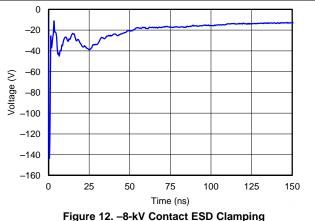
For this application, the audio signal voltage range is -3 V to 3 V. The V_{RWM} for the TVS is -5.5 V to 5.5 V; therefore, the bidirectional TVS will not break down during normal operation.

Next, consider the frequency content of this audio signal. In this application with the class AB amplifier, the frequency content is from 20 Hz to 20 kHz; ensure that the TVS I/O capacitance will not distort this signal by filtering it. With TPD2E1B06 typical capacitance of 0.85 pF, which leads to a typical 3-dB bandwidth of more than 3 GHz, this diode has way sufficient bandwidth to pass the audio signal without distorting it.

Finally, the human interface in this application requires above standard Level 4 IEC 61000-4-2 system-level ESD protection (±8-kV Contact and ±15-kV Air-Gap). TPD2E1B06 can survive at least ±10-kV Contact and ±15-kV Air-Gap. Therefore, the device can provide sufficient ESD protection for the interface, even though the requirements are stringent. For any TVS diode to provide the full range of ESD protection capabilities, as well as to minimize the noise and EMI disturbances the board will see during ESD events, a system designer must use proper board layout of their TVS ESD protection diodes. See *Layout* for instructions on properly laying out the TPD2E1B06.

8.2.3 Application Curves





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9 Power Supply Recommendations

This TPD2E1B06 is a passive TVS diode-based ESD protection device so it does not have any power requirements. Take care not to violate the maximum voltage specifications for each pin.

10 Layout

10.1 Layout Guidelines

- The optimum placement of the TPD2E1B06 is as close to the connector as possible. EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures. The printed-circuit board (PCB) designer must minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces, which are between the TVS and the connector.
- Route the protected traces as straight as possible.
- Avoid sharp corners on the protected traces. Electric fields tend to build up on corners, increasing EMI coupling.
- Use thick and short traces for the ground pins

10.2 Layout Examples

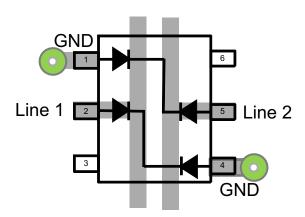


Figure 13. Routing Option 1

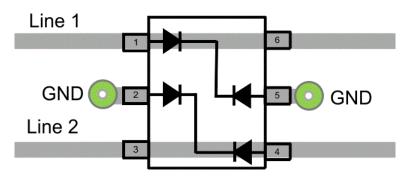


Figure 14. Routing Option 2



11 Device and Documentation Support

11.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Lise

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.2 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

11.3 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.4 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
TPD2E1B06DRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	NIPDAU NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(DUH, DUL) DUG
TPD2E1B06DRLR.B	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(DUH, DUL) DUG
TPD2E1B06DRLRG4	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	DUL
TPD2E1B06DRLRG4.B	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	DUL

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPD2	E1B06DRLR	SOT-5X3	DRL	6	4000	180.0	8.4	2.0	1.8	0.75	4.0	8.0	Q3
TPD2E	1B06DRLRG4	SOT-5X3	DRL	6	4000	180.0	8.4	2.0	1.8	0.75	4.0	8.0	Q3

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPD2E1B06DRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPD2E1B06DRLRG4	SOT-5X3	DRL	6	4000	210.0	185.0	35.0



PLASTIC SMALL OUTLINE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-293 Variation UAAD



PLASTIC SMALL OUTLINE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.7. Land pattern design aligns to IPC-610, Bottom Termination Component (BTC) solder joint inspection criteria.



PLASTIC SMALL OUTLINE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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